

Customer No.: 31561
Docket No.: 11182-US-PA
Application No.: 10/710,582

In The Claims

1. (Currently amended) A method of fabricating a flip chip ball grid array (FC-BGA) package, comprising:

providing a substrate having a first circuit surface, a second circuit surface, and a substrate core layer with plurality of openings, wherein the substrate core layer is disposed on the first circuit surface of the substrate comprising a first surface and a second surface, wherein the first surface comprises a plurality of cavities;

adhering a plurality of flip chips to the first circuit surface ~~cavities~~ of the substrate through the openings of the substrate core layer;

~~filling an underfill material between the substrate and the flip chips;~~

performing a ball placement step for attaching a plurality of solder balls to the second circuit surface ~~the second surface of the substrate;~~ and

singulating the substrate for separating portions of the substrate having the flip chips adhered thereon, wherein the substrate core layer is removed away.

2. (currently amended) The method of claim 1, further comprising a glue sealing step for filling a sealing glue material into the ~~cavities~~ openings to cover the flip chips ~~after the step of filling the underfill material.~~

3-7. (cancelled)

8. (New) The method of claim 1, the step of adhering the flip chips to the first circuit surface of the substrate further comprising filling an underfill material between the substrate and

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the flip chips.